NS7520, NS9360, & NS9750

Recommended Handling & Reflow Conditions

Product packaging is RoHS compliant and Pb-free

NetSilicon
A Digi International® Company

Handling for Moisture Sensitive Products

CAUTION :

Surface mount products may crack when thermal stress is applied during surface mount assembly if they absorb atmospheric moisture.

Please observe the following precautions:

1. The moisture barrier bag may be stored unopened 12 months at or below 30°C / 90% Relative Humidity
2. After opening the moisture proof bag, packages should be assembled **<u>within 1 week</u>** in an environment less than 30°C / 60% Relative Humidity.
3. If upon opening, the moisture indicator card shows humidity above 30% or the expiration date has passed, packages may still be used after a bake of 20 hrs at 125°C.

   <u>Caution:</u> If the packing material is likely to melt at 125°C, heatproof tray or aluminum magazine must be used for high temperature.
4. <u>Expiration date</u>: 12 months from sealing date imprinted near the heat-seal.

Reflow Conditions for Pb-free Products

Recommended temperature profile for infrared or convection reflow

(a) Complete infrared reflow process within 30~50 seconds at a package surface temperature, which is more than 230°C and less than 260°C.

(b) Refer to Figure1 for an example of a good temperature profile for infrared or convection reflow.

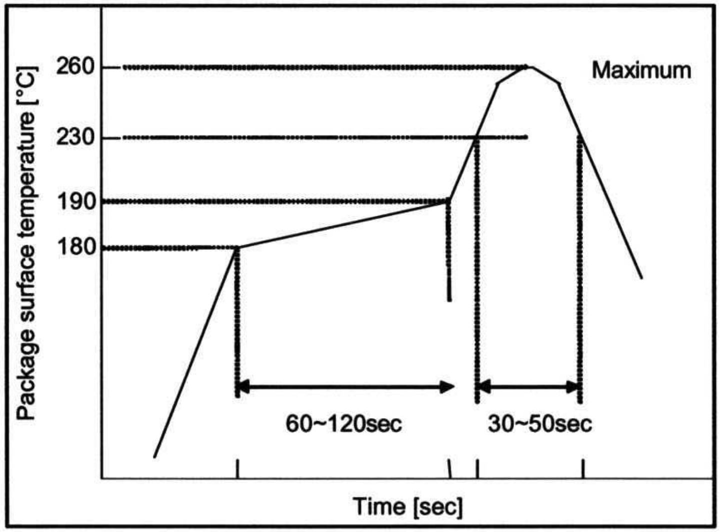

Figure 1 Sample Temperature Profile for Infrared or Convection Reflow

*This temperature profile shows maximum guaranteed device temperature. The profile is a typical condition of solder reflow. Please set up the optimum temperature profile conditions within the Figure 1 profile, according to the material of the solder paste and other conditions.